

TO:	文件编号	HXA-L05-24(02)
	发行日期	2015年11月27日

## 承认规格书

种类: 功率电感

系列号: HXCD75N-Series

客户料号: \_\_\_\_\_

客户承认栏	
承认日期	年 月 日

(贵司承认后请签署一份返回华信安电子, 谢谢!)

厦门华信安电子科技有限公司技术质量部

承认	确认	作成
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**SMD Power Inductor**

**HXCD75N-Series**

**ECN HISTORY LIST**

REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	15/8/27	新发行	龙梅	梁峰	王亮
2.0	15/11/27	产品升级, 特性重新修订	龙梅	梁峰	王亮
备注					



# SMD Power Inductor

HXCD75N-Series

## 1. Features

1. Small and Low profile inductor
2. It corresponds to High current.
3. Simple and Shield structure.
4. Available tape and reel for auto insertion.
5. 100% Lead(Pb)-Free and RoHS compliant.

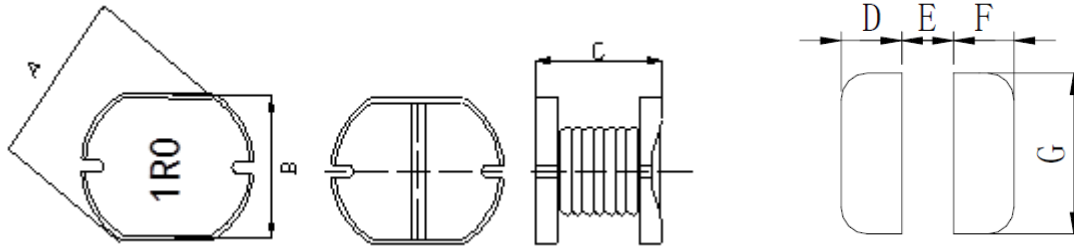


## 2. Applications

-For small DC/DC converter(cellular phone,LCD/LED/OLED display, HDD, DSC etc)

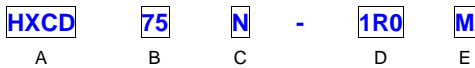
## 3. Dimensions

Recommend Land pattern



	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
HXCD75N	7.8±0.3	7.0±0.3	5.0±0.4	3.0	2.0	3.0	7.5

## 4. Part Numbering



A: Series

B: Dimension

C: Type

D: Inductance

E: Inductance Tolerance

A\*B\*C

1R0=1.0uh 100=10uh,101=100uh,102=1000uh

K=±10%, M=±20%,

marking direction cannot decide polarity. Color: Black, unidirectional.

No magnetic shielding

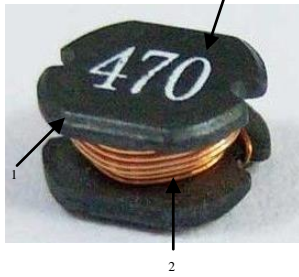
## 5. Specification

Part Number	Inductance L0 (uH) @ 0 A	Tolerance	Frequency (Hz/0.25V)	Rated current		DCR (mΩ) @25°C ± 20%.
				Saturation current I sat (A)	Tempetature current I rms (A)	
HXCD75N-1R5M	1.5	±20%	100K	6.10	6.50	10.5
HXCD75N-2R2M	2.2	±20%	100K	5.30	6.00	13.3
HXCD75N-3R3M	3.3	±20%	100K	4.20	5.50	17.0
HXCD75N-4R7M	4.7	±20%	100K	3.50	5.00	19.0
HXCD75N-5R6M	5.6	±20%	100K	3.15	4.80	22
HXCD75N-6R8M	6.8	±20%	100K	2.95	4.20	25
HXCD75N-100M	10.0	±20%	100K	2.50	3.50	36
HXCD75N-150M	15.0	±20%	100K	2.00	2.80	45
HXCD75N-220M	22.0	±20%	100K	1.70	2.30	66
HXCD75N-330M	33.0	±20%	100K	1.50	1.80	105
HXCD75N-470M	47.0	±20%	100K	1.20	1.50	140
HXCD75N-680M	68.0	±20%	100K	1.15	1.30	200
HXCD75N-101K	100.0	±10%	100K	0.87	1.10	266
HXCD75N-121K	120.0	±10%	100K	0.75	1.00	318
HXCD75N-181K	180.0	±10%	100K	0.70	0.85	530
HXCD75N-221K	220.0	±10%	100K	0.55	0.75	630
HXCD75N-331K	330.0	±10%	100K	0.50	0.60	750
HXCD75N-471K	470.0	±10%	100K	0.43	0.52	1050
HXCD75N-681K	680.0	±10%	100K	0.38	0.45	1600
HXCD75N-102K	1000.0	±10%	100K	0.30	0.40	2500

### Note:

1. All test data referenced to 25°C ambient.
2. Testing Instrument : L/Q: HP4284A,CH11025,CH3302,CH1320 ,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
3. Heat Rated Current (Irms) will cause the coil temperature rise approximately Δ t of 40°C (keep 1min.).
4. Saturation Current (Isat) will cause L0 to drop 30% typical. (keep quickly).
5. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
6. Special inquiries besides the above common used types can be met on your requirement.

## 6. Material List



NO	Items	Materials
1	Core	Ferrite core.
2	Wire	Polyester Wire or equivalent.
3	Ink	Halogen-free ketone

## 7. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125°C	
Storage temperature and Humidity range	-10~+40°C, 50~60%RH (Product without taping)	
<b>Electrical Performance Test</b>		
Inductance	Refer to standard electrical characteristics list.	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR Meter.
DCR		CH16502, Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	ΔL30% typical.	Saturation DC Current (Isat) will cause L0 to drop ΔL(%)(keep quickly).
Heat Rated Current (Irms)	Approximately ΔT≅40°C	Heat Rated Current (Irms) will cause the coil temperature rise ΔT(°C) without core loss. 1. Applied the allowed DC current(keep 1 min.). 2. Temperature measured by digital surface thermometer
<b>Reliability Test</b>		
High Temperature Exposure Test	Electric specifications should be satisfied	Temperature: 125±2°C. Duration: 1000±12hrs. Measured at room temperature after placing for 2 to 3hrs. (MIL-PRF-27)
Low Temperature Life Test		Temperature: -40±2°C. Duration: 500±12hrs. Measured at room temperature after placing for 2 to 3hrs.
Biased Humidity Test		Humidity: 85±3%RH. Temperature: 85±2°C. Duration: 1000±12hrs. Measured at room temperature after placing for 2 to 3hrs (AEC-Q200-REV C)
Thermal shock test		Condition for 1 cycle Step 1: -40+0 / -2°C 15±1 min. Step 2: Room temperature within ≅0.2 min. Step 3: +125+2 / -0°C 15±1min. Number of cycles: 300 Measured at room temperature after placing for 2 to 3 hrs. (AEC-Q200-REV C)
Vibration test		Frequency: 10-2000-10Hz for 20 min. Amplitude: Parts mounted within 2" from any secure point. Directions and times: X, Y, Z directions for 20 min. This cycle shall be performed 12 times in each of three mutually perpendicular directions (Total 12hours). (MIL-STD-202 Method 204 D Test condition B)
Ref low test		Pre-heat: 150±5°C Duration: 5 minutes Temperature: 260±5°C, 5-10 seconds (IPC/JEDEC J-STD-020C)
Solder test		After dip into flux, dip into solder 235±5°C, 4±1seconds Flux, solder for lead free (ANSI /J-STD-002C Method B)

## 8. Soldering and Mounting

### (1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. ISND terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

### (2) Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

### (3) Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Preheat circuit and products to 150°C  
355°C tip temperature (max)

Never contact the ceramic with the iron tip  
1.0mm tip diameter (max)

Use a 20 watt soldering iron with tip diameter of 1.0mm  
Limit soldering time to 4-5sec.

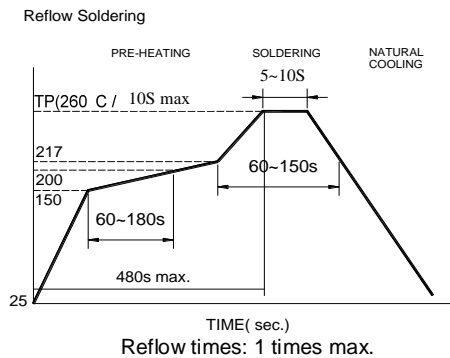


Fig.1

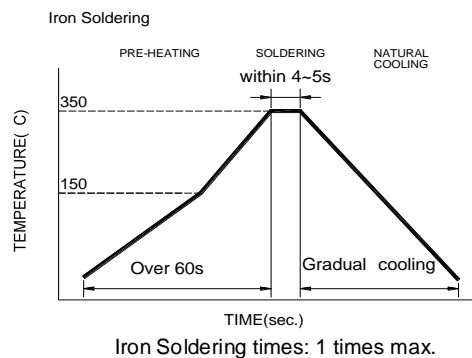
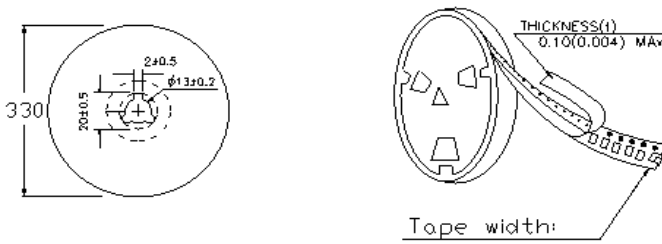


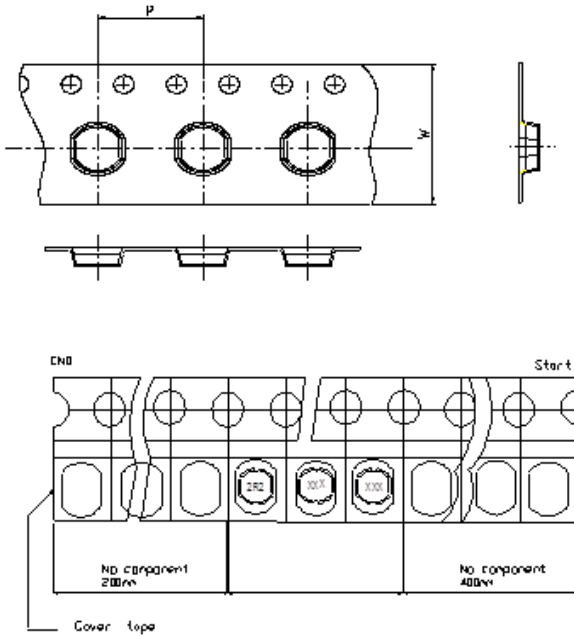
Fig.2

## 9. Packaging Information

### (1) Reel Dimension

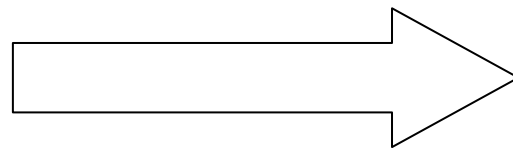


### (2) Tape Dimension



W	16
P	12

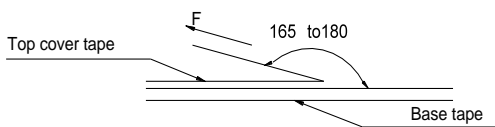
Unreeling  
Directio



### (3) Packaging Quantity

HXCD	75
Chip / Reel	1000

### (4) Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-C-2003 of 4.11 stadnard).

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

#### Application Notice

##### Storage Conditions

To maintain the solderability of terminal electrodes:

1. ISND products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40 °C and 60% RH.
3. Recommended products should be used within 12 months form the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

##### Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

单击下面可查看定价，库存，交付和生命周期等信息

[>>ISND\(华信安\)](#)